

## 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

## Notification# 20161209005 Datasheet for TPD1E04U04 Change Notification

**Date:** December 22, 2016 **To:** Newark/Farnell PCN

#### Dear Customer:

This is a notice of change to a product data sheet for a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN www admin team@list.ti.com).

Sincerely,

PCN Team SC Business Services

# 20161209005 Data Sheet Change Notification Attachments

### **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

**DEVICE**TPD1E04U04DPLT

**CUSTOMER PART NUMBER** 

null

Technical details of this Product Change follow on the next page(s).

PCN	Num	ber:	201	612090	005			PCN Da	ite:	Dec	22, 2016
Title	e:	Datasheet for	- TPD:	1E04U0	)4						•
Cus	tome	r Contact:	PCN A	Manager					De	ot:	Quality Services
			: 22, 2017								
	nge T	•									
	Assembly Site				☐ Design ☐ Wafer Bum						r Bump Site
Ħ	Assembly Process			□ Data Sheet     □ Data Sheet				Ħ	Wafer Bump Material		
	Assembly Materials			Ħ	Part number change					r Bump Process	
Mechanical Specification				Test Site				Wafer Fab Site			
Packing/Shipping/Labeling				Test Process				Wafer Fab Materials			
								Wafe	r Fab Process		
					No	otification	on Det	ails			
Des	cripti	on of Chang	e:								
The	The following change history provides further details.										
INSTRUMENTS  SLVSDG4B – MARCH 2016 – REVISED AUGUST 2016											
	Changes from Revision A (April 2016) to Revision B										
•	Added new DPL package										
Added DPL Package information in the Absolute Maximum Ratings table											
	Added Thermal information for DPL package in the <i>Thermal Information</i> table     Changed Vbr min spec from 5 V to 4.5 V in the <i>Electrical Characteristics</i> table										
The	datasl	neet number	will b	e chan	ging	].					
De	vice Fa	amily				Change	From:				Change To:
TPI	TPD1E04U04				SLVSDG	4A				SLVSDG4B	
http	)://ww	nges may be w.ti.com/pro					t links p	rovided.			
		or Change:									
	To more accurately reflect device characteristics.										
Ant	icipat	ed impact o	n Fit,	Form	, Fι	ınction, Ç	<b>Quality</b>	or Relial	bility	(pos	itive / negative):
		ated impact. Jal device.	This i	s a spe	cifi	cation cha	nge ann	ounceme	nt o	nly. Th	ere are no changes
Cha	Changes to product identification resulting from this PCN:										
Non		•									
Pro	duct A	Affected:									
TPE	D1E04U	J04DPLR	TPD:	LE04U0	4DP	LT	TPD1E0	4U04DPYF	₹	TF	PD1E04U04DPYT
			1								

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com